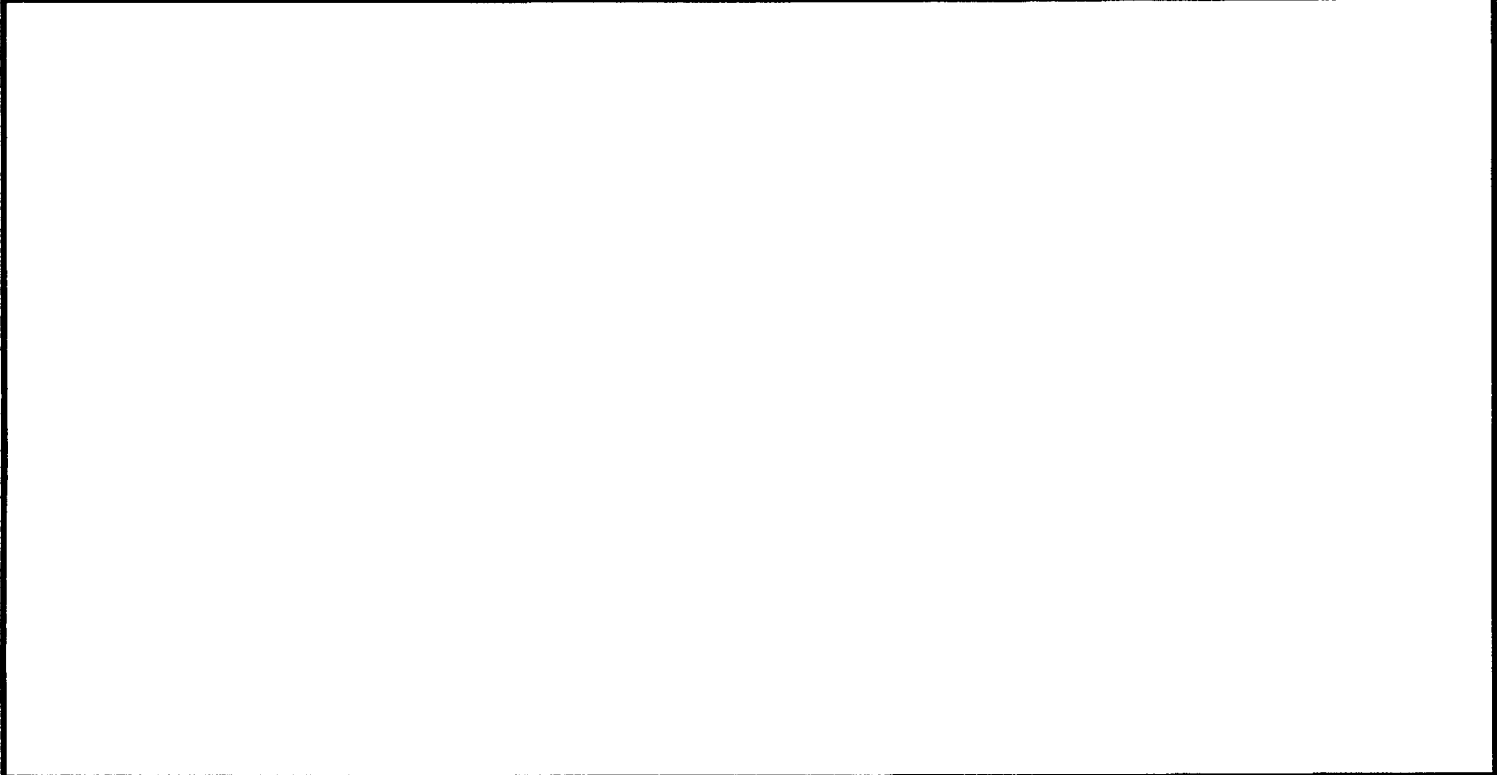


REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Add device type 05. Update boilerplate. Make corrections to figure 4. Editorial changes throughout.	94-06-22	M.A. Frye



REV																				
SHEET																				
REV	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A
SHEET	15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	30	31	32	33	34
REV STATUS OF SHEETS		REV		A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A	A
		SHEET		1	2	3	4	5	6	7	8	9	10	11	12	13	14			

<p align="center">STANDARDIZED MILITARY DRAWING</p> <p>THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE</p> <p>AMSC N/A</p>	PREPARED BY Kenneth Rice	DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		
	CHECKED BY Charles Reusing			
	APPROVED BY Michael A. Frye	MICROCIRCUIT, MEMORY, DIGITAL, CMOS, 4K X 9 PARALLEL SERIAL FIFO, MONOLITHIC SILICON		
	DRAWING APPROVAL DATE 12 MAY 1990			
	REVISION LEVEL A			
		SHEET 1 OF 34		

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 DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E256-94

■ 9004708 0002153 501 ■

1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 Device type(s). The device type(s) shall identify the circuit function as follows:

Device type	Generic number	Circuit function	Access time
01	(see 6.6)	4k X 9-bit parallel-serial FIFO	120 ns
02	(see 6.6)	4k X 9-bit parallel-serial FIFO	80 ns
03	(see 6.6)	4k X 9-bit parallel-serial FIFO	65 ns
04	(see 6.6)	4k X 9-bit parallel-serial FIFO	50 ns
05	(see 6.6)	4k X 9-bit parallel-serial FIFO	40 ns

1.2.2 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
Q	GDIP1-T40 or CDIP2-T40	40	Dual-in-line
X	CQCC1-N44	44	Square leadless chip carrier

1.2.3 Lead finish. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein). Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

Terminal voltage with respect to ground	-0.5 V dc to +7.0 V dc
DC output current	50 mA
Storage temperature range	-65°C to +150°C
Maximum power dissipation (P _D)	1.0 W
Lead temperature (soldering, 10 seconds)	+260°C
Thermal resistance, junction-to-case (θ _{JC})	See MIL-STD-1835
Junction temperature (T _J)	+150°C 1/

1.4 Recommended operating conditions.

Supply voltage range (V _{CC})	4.5 V dc to 5.5 V dc
Minimum high level input voltage (V _{IH})	2.2 V dc
Maximum low level input voltage (V _{IL})	+0.8 V dc 2/
Case operating temperature range (T _C)	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and bulletin. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

1/ Maximum junction temperature may be increased to +175°C during burn-in and steady-state life.
 2/ 1.5 V undershoots are allowed for 10 ns once per cycle.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	5962-89943
	REVISION LEVEL A	SHEET 2

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9004708 0002154 448

SPECIFICATION

MILITARY

MIL-I-38535 - Integrated Circuits (Microcircuits) Manufacturing, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.
MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-I-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-I-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-I-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth tables. The truth tables shall be as specified on figure 2.

3.2.3 Case outline(s). The case outline(s) shall be in accordance with 1.2.2 herein.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89943
		REVISION LEVEL A	SHEET 3

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9004708 0002155 384

TABLE 1. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified		Device type	Group A subgroups	Limits		Unit
						Min	Max	
Input leakage current	I _{LI}	0.4 V ≤ V _{IN} ≤ V _{OUT}		All	1,2,3	-10	10	μA
Output leakage current	I _{LO}	0.4 V ≤ V _{OUT} ≤ V _{CC} , $\bar{R} \geq V_{IH}$		All	1,2,3	-10	10	μA
Output low voltage	V _{OL}	V _{CC} = 4.5 V, V _{IL} = 0.8 V, V _{IH} = 2.2 V	SO, I _{OUT} = 16 mA	All	1,2,3		0.4	V
			All other outputs, I _{OUT} = 8.0 mA				0.4	
Output high voltage	V _{OH}	V _{CC} = 4.5 V, V _{IL} = 0.8 V, V _{IH} = 2.2 V	SO, I _{OUT} = -8.0 mA	All	1,2,3	2.4		V
			All other outputs, I _{OUT} = -2.0 mA			2.4		
Power supply current	I _{CC1}	f = f _S , outputs open, V _{CC} = 5.5 V		All	1,2,3		160	mA
Average standby current	I _{CC2}	$\bar{R} = \bar{W} = \bar{RS} = \overline{FL/RT} = V_{IH}$, outputs open		All	1,2,3		25	mA
Power down current	I _{CC3}	$\bar{RS} = \overline{FL/RT} = \bar{W} = \bar{R} = V_{CC} - 0.2$ V, all other inputs ≥ V _{CC} - 0.2 V or ≤ 0.2 V, outputs open		All	1,2,3		4.0	mA
Input capacitance 1/	C _{IN}	V _I = 0 V, f = 1.0 MHz, T _A = +25°C, see 4.3.1c		All	4		10	pF
Output capacitance 1/	C _{OUT}	V _O = 0 V, f = 1.0 MHz, T _A = +25°C, see 4.3.1c		All	4		12	pF
Functional tests		See 4.3.1d		All	7,8A,8B			
Parallel I/O shift frequency	f _S	C _L = 30 pF, see figures 3 and 4		01	9,10,11		7.0	MHz
				02		10		
				03		12.5		
				04		15		
				05		20		

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89943
		REVISION LEVEL A	SHEET 4

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9004708 0002156 210

TABLE 1. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Serial-out shift frequency	f _{SOCP}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		25	MHz
			02			28	
			03			33	
			04			40	
			05			50	
Serial-in shift frequency	f _{SICP}		01	9,10,11		25	MHz
			02			28	
			03			33	
			04			40	
			05			50	

PARALLEL OUTPUT MODE TIMINGS

Access time	t _A	C _L = 30 pF, see figures 3 and 4	01	9,10,11		120	ns
			02			80	
			03			65	
			04			50	
			05			40	
Read recovery time	t _{RR}		01,02	9,10,11	20		ns
			03,04		15		
			05		10		
Read pulse width	t _{RPW}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		

See footnotes at end of table.

<p>STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</p>	<p>SIZE A</p>		<p>5962-89943</p>
		<p>REVISION LEVEL A</p>	<p>SHEET 5</p>

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9004708 0002157 157

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Read cycle time	t _{RC}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	140		ns
			02		100		
			03		80		
			04		65		
			05		50		
Write pulse low to data bus at low Z <u>Z</u> /	t _{WLZ}		01,02	9,10,11	20		ns
			03,04		15		
			05		5		
Read pulse low to data bus at low Z <u>Z</u> /	t _{RLZ}		01-04	9,10,11	10		ns
			05		5		
Read pulse high to data bus at high Z <u>Z</u> /	t _{RHZ}		01,02	9,10,11		35	ns
			03,04			30	
			05			25	
Data valid from read pulse high	t _{DV}		ALL	9,10,11	5.0		ns

PARALLEL INPUT MODE TIMINGS

Data setup time	t _{DS}	C _L = 30 pF, see figures 3 and 4	01,02	9,10,11	40		ns
			03,04		30		
			05		20		
Data hold time	t _{DH}		01-03	9,10,11	10		ns
			04		5.0		
			05		0		
Write cycle time	t _{WC}		01	9,10,11	140		ns
			02		100		
			03		80		
			04		65		
			05		50		

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89943
		REVISION LEVEL A	SHEET 6

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9004708 0002158 093

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _c ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Write pulse width	t _{WPW}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Write recovery time	t _{WR}		01,02	9,10,11	20		ns
			03,04		15		
			05		10		

RESET TIMINGS

Reset cycle time	t _{RSC}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	140		ns
			02		100		
			03		80		
			04		65		
			05		50		
Reset pulse width	t _{RS}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Reset setup time	t _{RSS}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Reset recovery time	t _{RSR}		01,02	9,10,11	20		ns
			03,04		15		
			05		10		

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89943
		REVISION LEVEL A	SHEET 7

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9004708 0002159 T2T

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _c ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
RESET TO FLAGS DELAYS							
Reset to \overline{EF} , \overline{AEF} , and $\overline{EF+1}$ low	t _{RSF1}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			50	
Reset to \overline{HF} , \overline{FF} , and $\overline{FF-1}$ high	t _{RSF2}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			50	
RESET TO TIME DELAYED OUTPUTS - SERIAL MODE ONLY							
Reset going low to Q ₀₋₈ low	t _{RSQL}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	105		ns
			02			65	
			03			50	
			04			35	
			05			20	
Reset going high to Q ₀₋₈ high	t _{RSQH}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	105		ns
			02			65	
			03			50	
			04			35	
			05			20	
Reset going low to D ₀₋₈ low	t _{RSDL}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	105		ns
			02			65	
			03			50	
			04			35	
			05			20	

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89943
		REVISION LEVEL A	SHEET 8

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9004708 0002160 741

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _c ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V Unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
RETRANSMIT TIMINGS							
Retransmit cycle time	t _{RTC}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	140		ns
			02		100		
			03		80		
			04		65		
			05		50		
Retransmit pulse width	t _{RT}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Retransmit setup time	t _{RTS}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Retransmit recovery time	t _{RTR}		01,02	9,10,11	20		ns
			03,04		15		
			05		10		

PARALLEL MODE FLAG PROPAGATION DELAYS

Read low to $\overline{\text{EF}}$ low	t _{REF}	C _L = 30 pF, see figures 3 and 4	01-03	9,10,11	60	ns
			04		45	
			05		35	
Read high to $\overline{\text{FF}}$ high	t _{RFF}		01-03	9,10,11	60	ns
			04		45	
			05		35	

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89943
		REVISION LEVEL A	SHEET 9

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■ 9004708 0002161 688 ■

TABLE 1. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _c ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Read high to <u>transitioning</u> HF, AEF, and FF-1	t _{RF}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			50	
Read low to <u>transitioning</u> AEF and EF+1	t _{RE}		01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			45	
Read pulse width after EF high	t _{RPE}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Write high to EF high	t _{WEF}		01-03	9,10,11		60	ns
			04			45	
			05			35	
Write low to FF low	t _{WFF}		01-03	9,10,11		60	ns
			04			45	
			05			35	
Write low to <u>transitioning</u> HF, AEF, and FF-1	t _{WF}		01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			50	

See footnotes at end of table.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89943
		REVISION LEVEL A	SHEET 10

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9004708 0002162 514

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
Write high to <u>transitioning</u> AEF and EF+1	t _{WE}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		140	ns
			02			100	
			03			80	
			04			65	
			05			50	
Write pulse width after FF high	t _{WPF}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		

DEPTH EXPANSION MODE DELAYS

Read/write to $\overline{X0}$ low	t _{XOL}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		120	ns
			02			80	
			03			65	
			04			50	
			05			40	
Read/write to $\overline{X0}$ high	t _{XOH}		01	9,10,11		120	ns
			02			80	
			03			65	
			04			50	
			05			40	
\overline{XI} pulse width	t _{XI}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		

See footnotes at end of table.

<p align="center">STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</p>	<p align="center">SIZE A</p>		<p align="center">5962-89943</p>
		<p align="center">REVISION LEVEL A</p>	<p align="center">SHEET 11</p>

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9004708 0002163 450

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
\bar{X} I recovery time	t _{XIR}	C _L = 30 pF, see figures 3 and 4	All	9,10,11	10		ns
\bar{X} I setup time	t _{XIS}		All	9,10,11	15		ns

SERIAL INPUT MODE TIMINGS

Serial data in setup time to SICIP rising edge	t _{S2}	C _L = 30 pF, see figures 3 and 4	01,02	9,10,11	20		ns
			03,04		15		
			05		12		
Serial data in hold time from SICIP rising edge	t _{H2}		01,02	9,10,11	5.0		ns
			03-05		0		
SIX setup time to SICIP rising edge	t _{S3}		All	9,10,11	5.0		ns
\bar{W} setup time to SICIP rising edge	t _{S4}		All	9,10,11	5.0		ns
\bar{W} hold time to SICIP rising edge	t _{H4}		01	9,10,11	15		ns
			02		12		
			03		10		
			04,05		7.0		
Serial in clock width high/low	t _{SICW}		01,02	9,10,11	15		ns
			03,04		10		
			05		8		
\bar{S} I/PI setup time to SICIP rising edge	t _{S5}		01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		

See footnotes at end of table.

<p>STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444</p>	<p>SIZE A</p>		<p>5962-89943</p>
		<p>REVISION LEVEL A</p>	<p>SHEET 12</p>

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
SERIAL OUTPUT MODE TIMINGS							
SO/PO setup time to SOCP rising edge	t _{S6}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
SOX setup time to SOCP rising edge	t _{S7}		All	9,10,11	5.0		ns
R setup time to SOCP rising edge	t _{S8}		All	9,10,11	5.0		ns
R hold time to SOCP rising edge	t _{H8}		01	9,10,11	15		ns
			02		12		
			03		10		
			04,05		7.0		
Serial in clock width high/low	t _{SOCW}		01,02	9,10,11	15		ns
			03,04		10		
			05		8		

SERIAL MODE RECOVERY TIMINGS

Recovery time SOCP after EF goes high	t _{REFSO}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	120		ns
			02		80		
			03		65		
			04		50		
			05		40		
Recovery time SICP after FF goes high	t _{RFFSI}		01,02	9,10,11	20		ns
			03-05		15		

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _C ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V Unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
SERIAL MODE FLAG PROPAGATION DELAYS							
SOCP rising edge (bit 0 - first word) to EF low	t _{SOCEF}	C _L = 30 pF, see figures 3 and 4	01-03	9,10,11		30	ns
			04,05			25	
SOCP rising edge (bit 0 - first word) to FF high	t _{SOCFF}		01,02	9,10,11		60	ns
			03			50	
			04			40	
			05			35	
SOCP rising edge (bit 0 - second word) to FF-1, HF, AEF, EF+1 high	t _{SOCF}		01,02	9,10,11		60	ns
			03			50	
			04			40	
			05			35	
SICP rising edge (bit 0 - first word) to EF high	t _{SICEF}		01-03	9,10,11		80	ns
			04			65	
			05			50	
SICP rising edge (bit 0 - first word) to FF low	t _{SICFF}		01,02	9,10,11		60	ns
			03			50	
			04			40	
			05			35	
SICP rising edge (bit 0 - second word) to EF+1, HF, AEF, FF-1 high	t _{SICF}		01-03	9,10,11		80	ns
			04			65	
			05			50	

SERIAL INPUT MODE DELAYS

SICP rising edge to D <u>2</u> /	t _{PD1}	C _L = 30 pF, see figures 3 and 4	01	9,10,11	5.0	35	ns
			02		5.0	30	
			03		5.0	25	
			04		5.0	20	
			05		5.0	17	

See footnotes at end of table.

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■ 9004708 0002166 16T ■

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T _c ≤ +125°C V _{SS} = 0 V, 4.5 V ≤ V _{CC} < 5.5 V unless otherwise specified	Device type	Group A subgroups	Limits		Unit
					Min	Max	
SERIAL OUTPUT MODE DELAYS							
SOCP rising edge to Q 2/	t _{PD2}	C _L = 30 pF, see figures 3 and 4	01,02	9,10,11	5.0	30	ns
			03		5.0	25	
			04		5.0	20	
			05		5.0	17	
SOCP rising edge to SO at high-Z 2/	t _{SOHZ}		01	9,10,11	5.0	30	ns
			02		5.0	25	
			03		5.0	20	
			04,05		5.0	16	
SOCP rising edge to SO at low-Z 2/	t _{SOLZ}		01	9,10,11	5.0	35	ns
			02		5.0	30	
			03-05		5.0	22	
SOCP rising edge to valid data on SO	t _{SOPD}		01	9,10,11		35	ns
			02			30	
			03			22	
			04,05			18	

OUTPUT ENABLE/DISABLE DELAYS

Output enable to high-Z (disable) 2/	t _{OEHZ}	C _L = 30 pF, see figures 3 and 4	01	9,10,11		30	ns
			02			25	
			03			20	
			04,05			16	
Output enable to low-Z (enable) 2/	t _{OELZ}		All	9,10,11	5.0		ns
Output enable to data valid (Q ₀₋₈)	t _{AOE}		01	9,10,11		35	ns
			02			30	
			03			25	
			04			22	
			05			20	

- 1/ Shall be tested initially and after any design or process changes which may affect this parameter, and therefore shall be guaranteed to the limits specified in table I.
 2/ May not be tested, but shall be guaranteed to the limits specified in table I.

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Device types	All	
	Q	X
Terminal number	Terminal symbol	
1	SO	\bar{W}
2	AEF	D ₄
3	FF-1	D ₃
4	FF	D ₂
5	Q ₀	D ₁
6	Q ₁	GND
7	Q ₂	D ₀
8	Q ₃	\bar{XI}
9	Q ₄	SO/PO
10	GND	SOX
11	R	SOCP
12	Q ₅	SO
13	Q ₆	AEF
14	Q ₇	FF-1
15	Q ₈	FF
16	$\bar{XO/HF}$	Q ₀
17	EF	GND
18	EF+1	Q ₁
19	OE	Q ₂
20	SI/PI	Q ₃
21	SIX	Q ₄
22	SICP	GND
23	SI	R
24	RS	Q ₅
25	FL/RT	Q ₆
26	D ₈	Q ₇
27	D ₇	Q ₈
28	D ₆	GND
29	D ₅	$\bar{XO/HF}$
30	V _{CC}	EF
31	W	EF+1
32	D ₄	OE
33	D ₃	SI/PI
34	D ₂	SIX
35	D ₁	SICP
36	D ₀	SI
37	\bar{XI}	RS
38	SO/PO	FL/RT
39	SOX	GND
40	SOCP	D ₈
41	---	D ₇
42	---	D ₆
43	---	D ₅
44	---	V _{CC}

FIGURE 1. Terminal connections.

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Reset and retransmit
Single device configuration/width expansion mode

Mode	Inputs			Internal status		Outputs		
	\overline{RS}	\overline{FL}	\overline{XI}	Read pointer	Write pointer	\overline{AEF} , \overline{EF} , $\overline{EF+1}$	\overline{FF} , $\overline{FF-1}$	\overline{HF}
Reset	0	X	0	Location zero	Location zero	0	1	1
Retransmit	1	0	0	Location zero	Unchanged	X	X	X
Read/Write	1	1	0	Increment $\frac{1}{2}$	Increment $\frac{1}{2}$	X	X	X

$\frac{1}{2}$ Pointer will increment if flag is high.

Reset and first load
Depth expansion/compound expansion mode

Mode	Inputs			Internal status		Outputs	
	\overline{RS}	\overline{FL}	\overline{XI}	Read pointer	Write pointer	\overline{EF}	\overline{FF}
Reset first device	0	0	$\frac{1}{2}$	Location zero	Location zero	0	1
Reset all other devices	0	1	$\frac{1}{2}$	Location zero	Location zero	0	1
Read/Write	1	X	$\frac{1}{2}$	X	X	X	X

$\frac{1}{2}$ \overline{XI} is connected to $\overline{X0}$ of previous device.

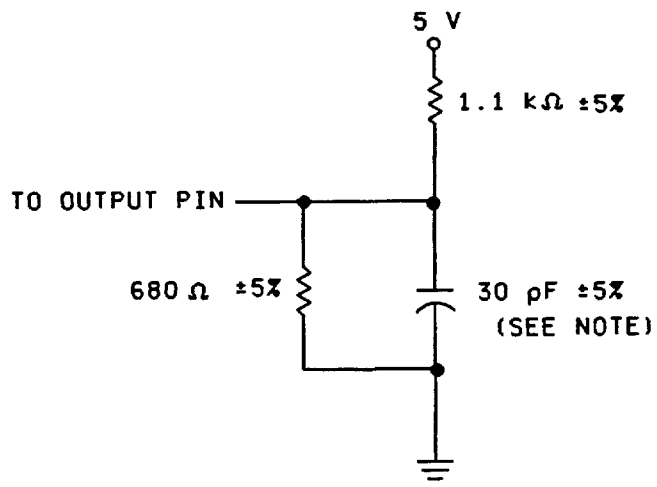
NOTE: \overline{RS} = Reset input, $\overline{FL}/\overline{RT}$ = First load/retransmit, \overline{EF} = Empty flag output, \overline{FF} = Full flag output, \overline{XI} = Expansion input, and \overline{HF} = Half-full flag output
 0 = Low level voltage
 1 = High level voltage
 X = Don't care

FIGURE 2. Truth tables.

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NOTE: C_L includes scope and jig capacitance.

AC test conditions

Input pulse levels	GND to 3.0 V
Input rise and fall times	3.0 ns
Input timing reference levels	1.5 V
Output reference levels	1.5 V

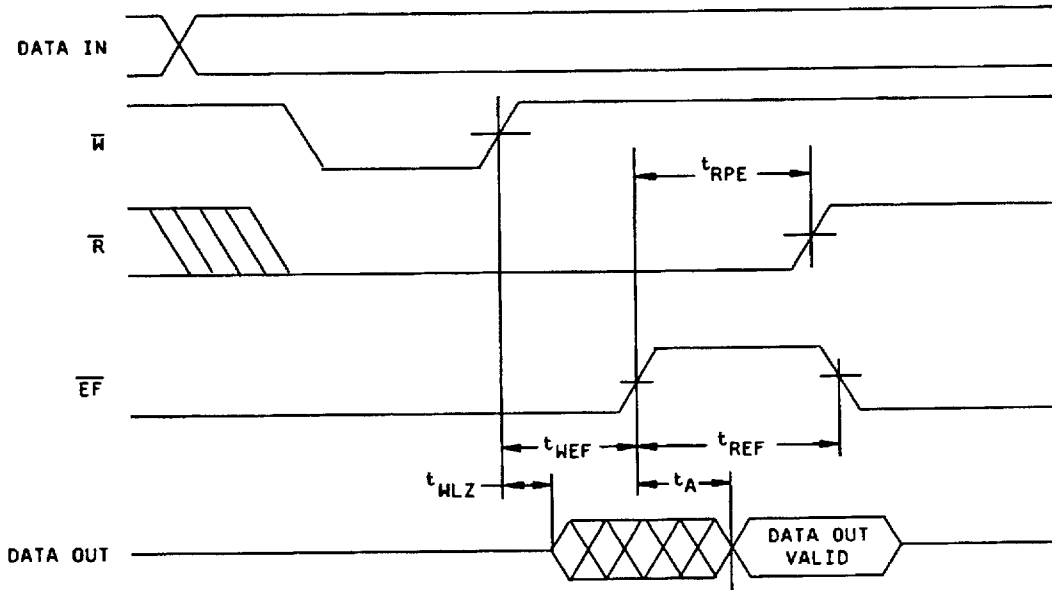
FIGURE 3. Output load circuit and ac test conditions.

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FIFO EMPTY BOUNDARY CONDITION TIMING



FIFO FULL BOUNDARY CONDITION TIMING

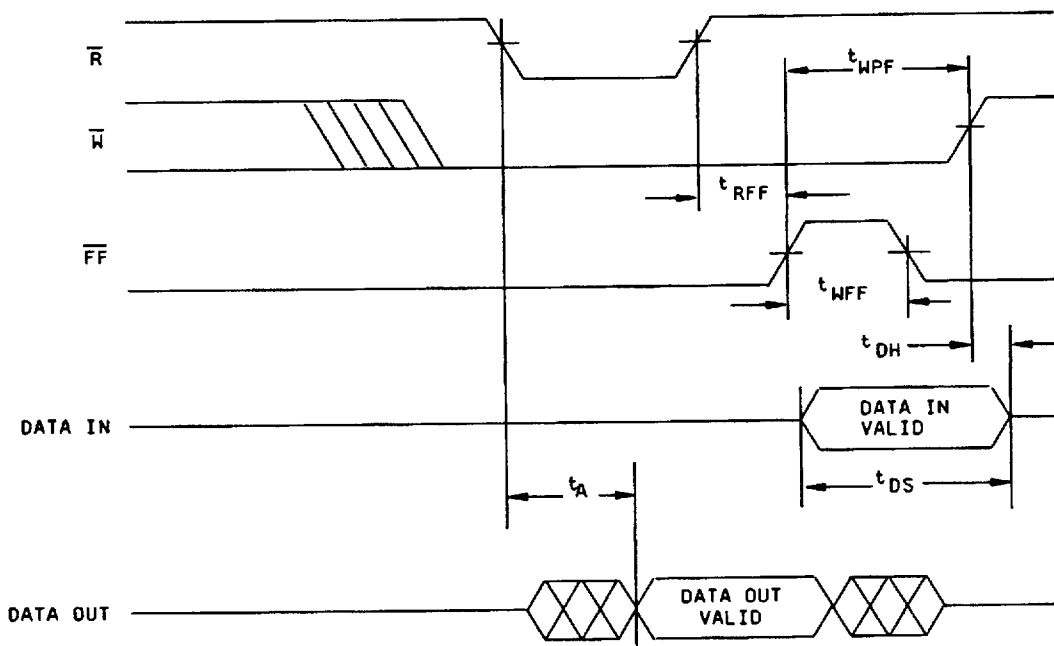


FIGURE 4. Timing waveforms.

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■ 9004708 0002171 527 ■

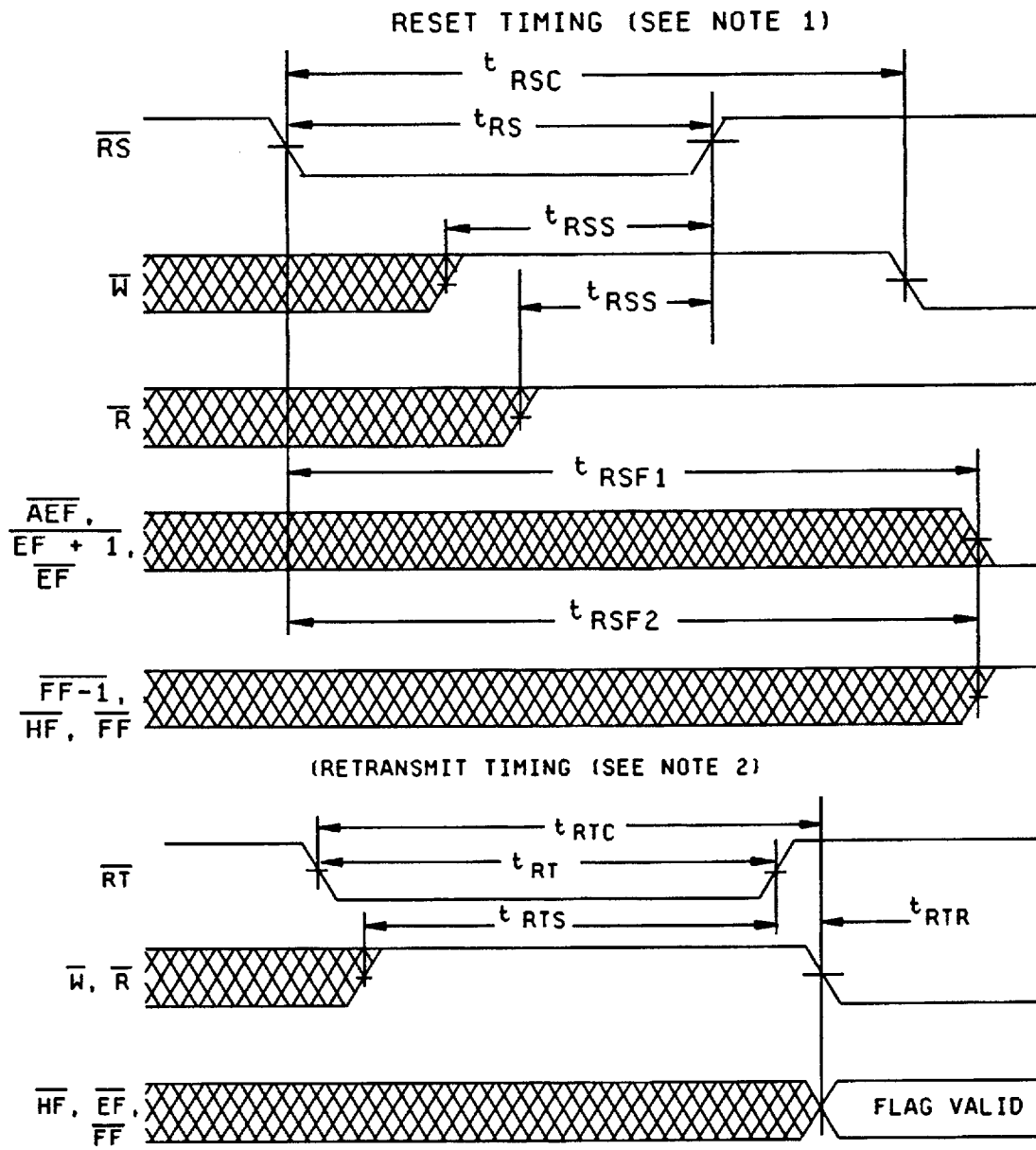


FIGURE 4. Timing waveforms - Continued.

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■ 9004708 0002172 463 ■

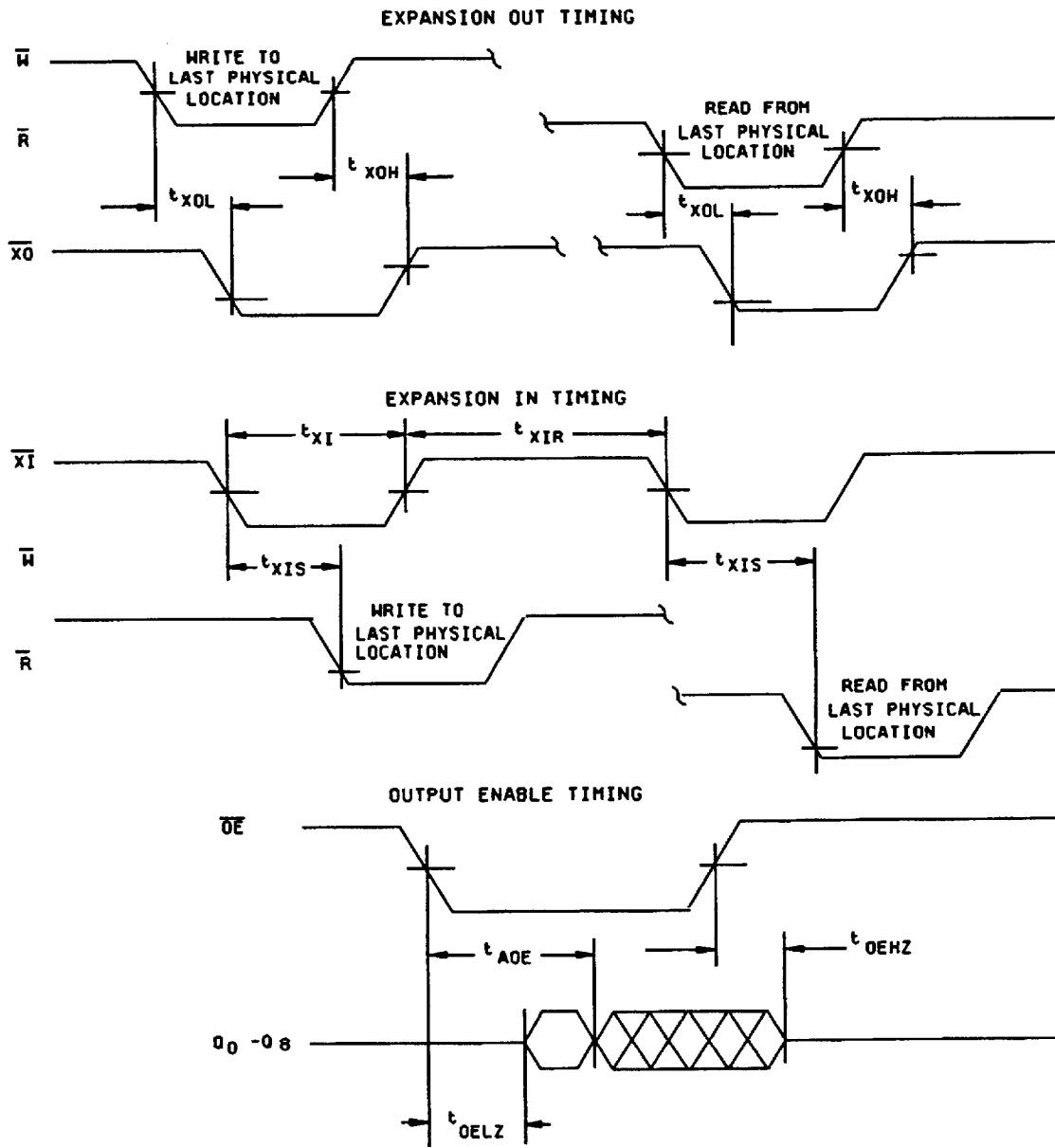


FIGURE 4. Timing waveforms - Continued.

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9004708 0002173 3TT

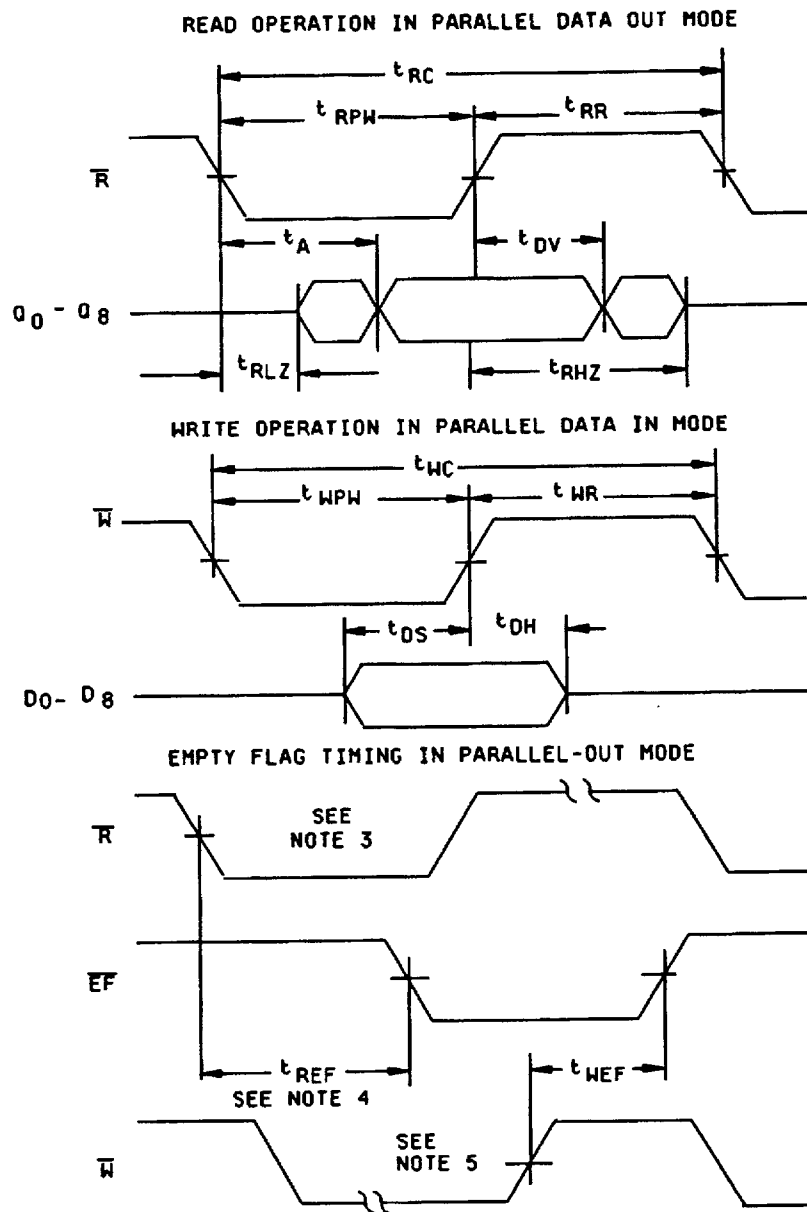


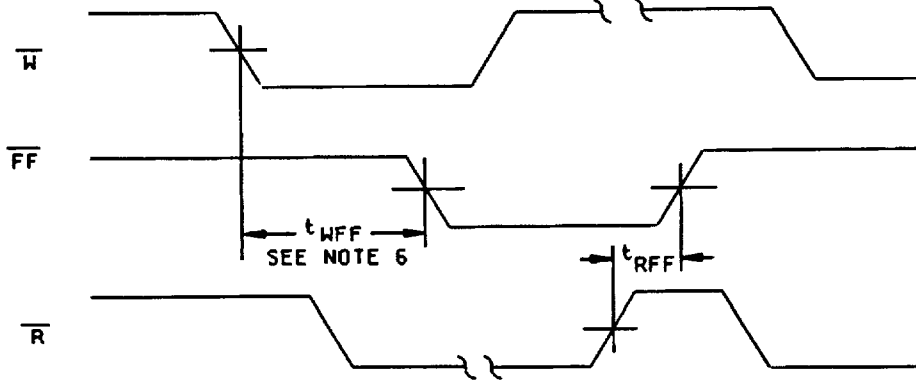
FIGURE 4. Timing waveforms - Continued.

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■ 9004708 0002174 236 ■

FULL FLAG TIMING IN PARALLEL-IN MODE



ALMOST-FULL, HALF-FULL, AND FULL-1 FLAG TIMING

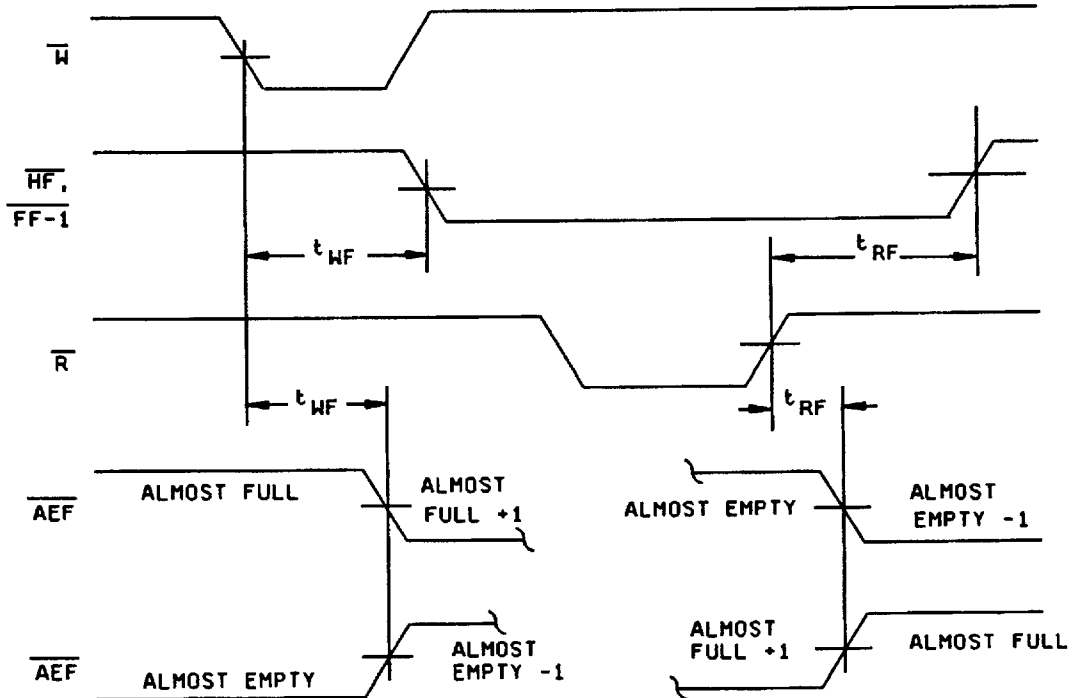


FIGURE 4. Timing waveforms - Continued.

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EMPTY +1 FLAG TIMINGS

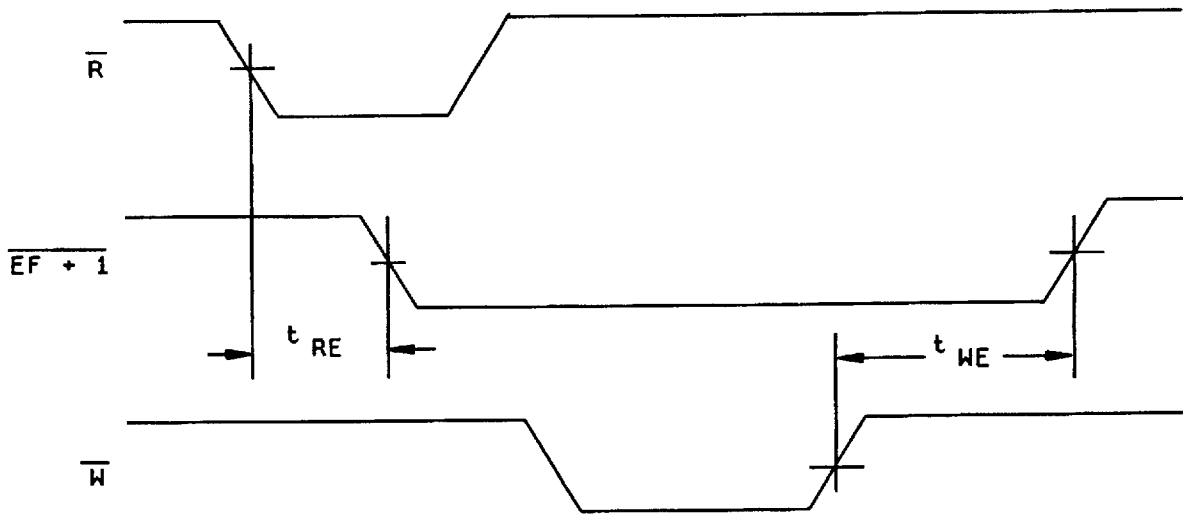


FIGURE 4. Timing waveforms - Continued.

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■ 9004708 0002176 009 ■

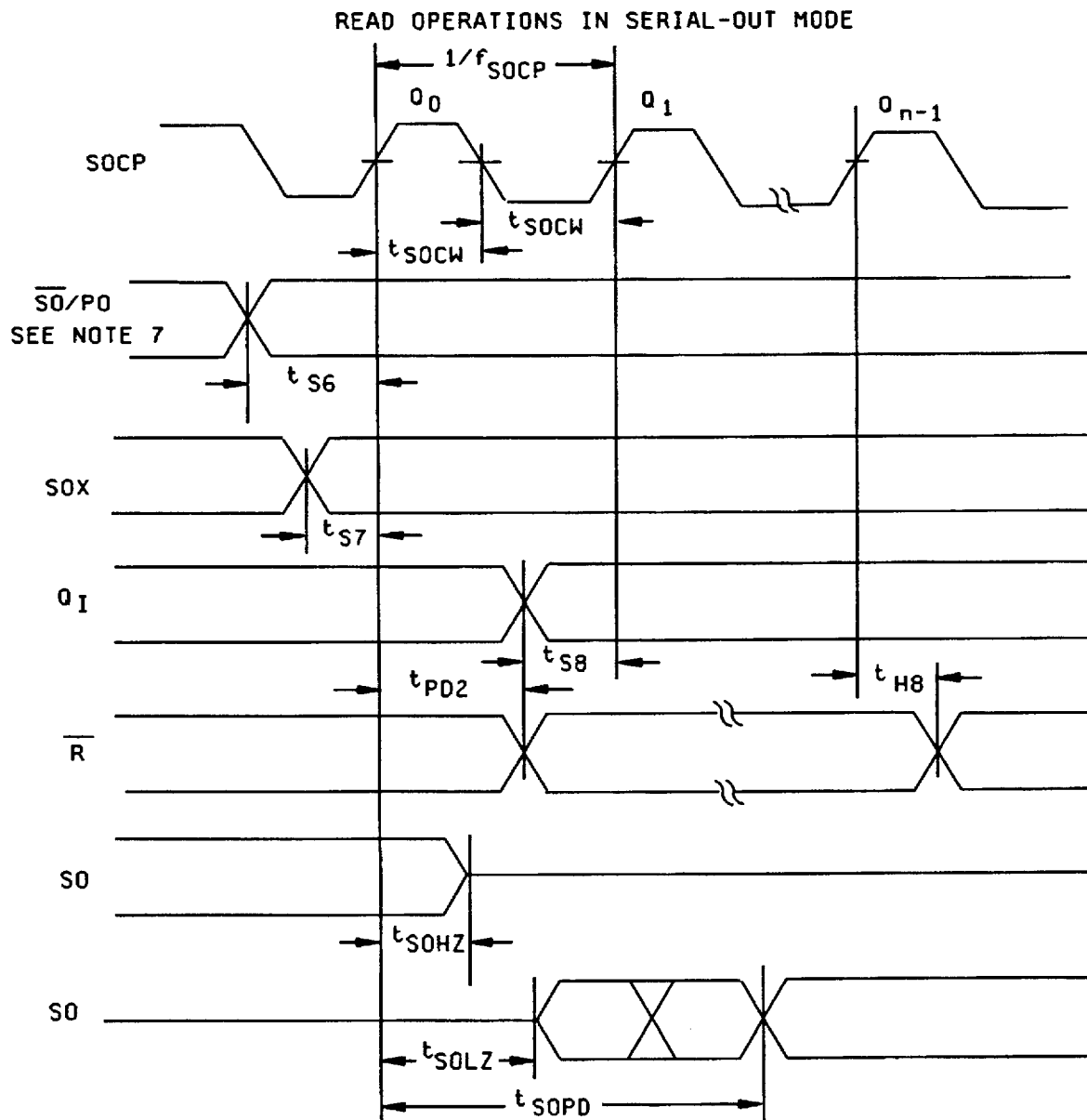


FIGURE 4. Timing waveforms - Continued.

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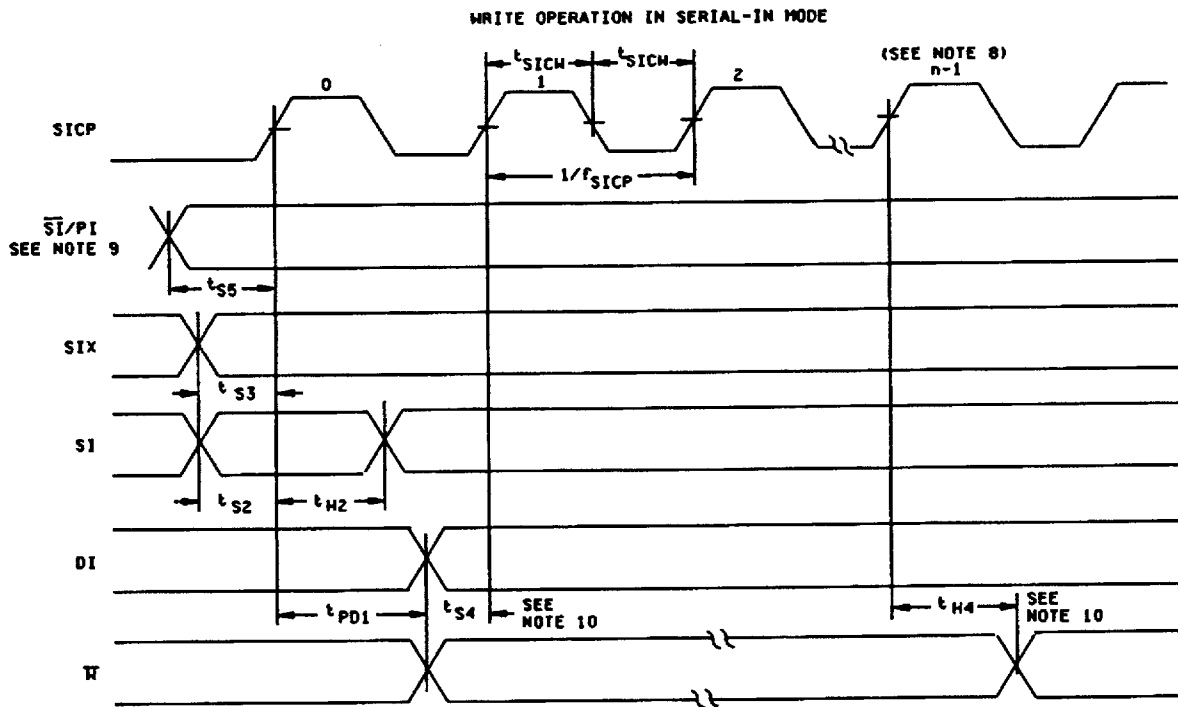


FIGURE 4. Timing waveforms - Continued.

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9004708 0002178 981

FULL FLAG AND FULL-1 FLAG DEASSERTION IN SERIAL-OUT MODE

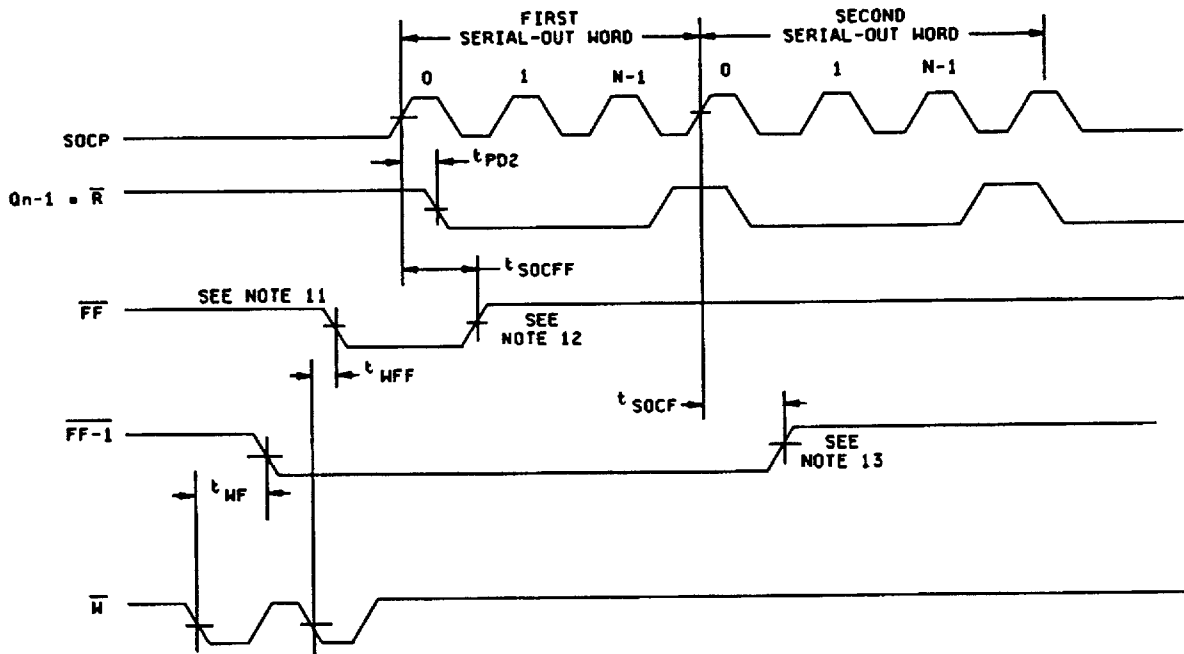


FIGURE 4. Timing waveforms - Continued.

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■ 9004708 0002179 818 ■

EMPTY FLAG AND EMPTY + 1 FLAG ASSERTATION IN THE SERIAL MODE.
FIFO BEING EMPTIED

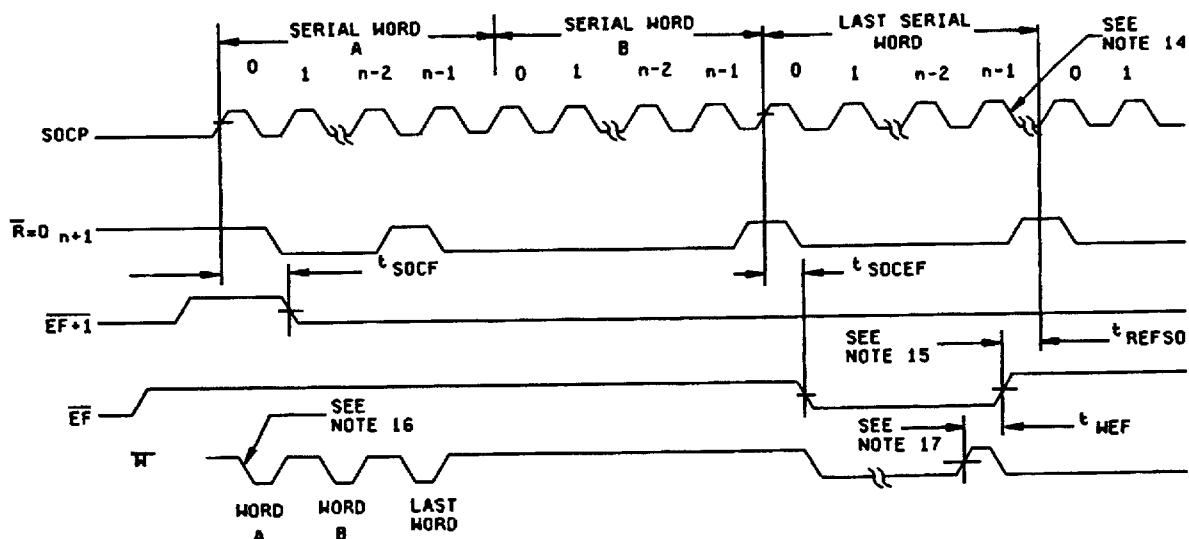


FIGURE 4. Timing waveforms - Continued.

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9004708 0002180 53T

Full flag and full - 1 flag assertion in the serial-in mode,
FIFO being filled

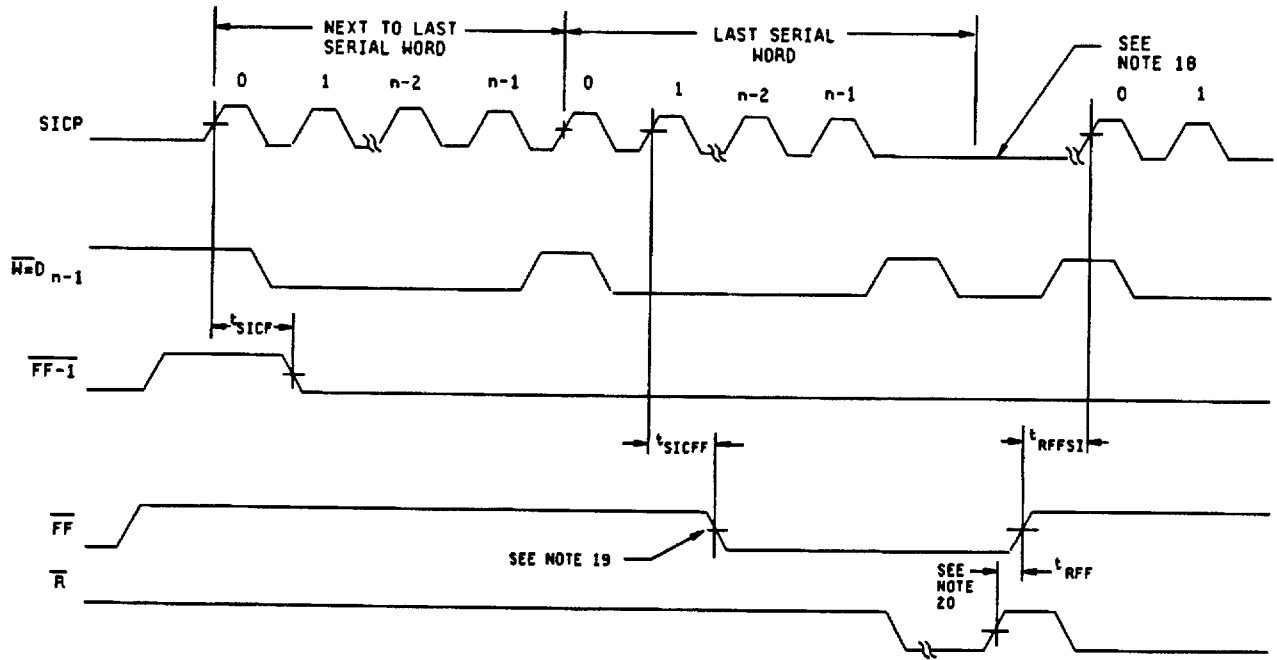


FIGURE 4. Timing waveforms - Continued.

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■ 9004708 0002181 476 ■

EMPTY FLAG AND EMPTY+1 FLAG DEASSERTION IN SERIAL-IN MODE

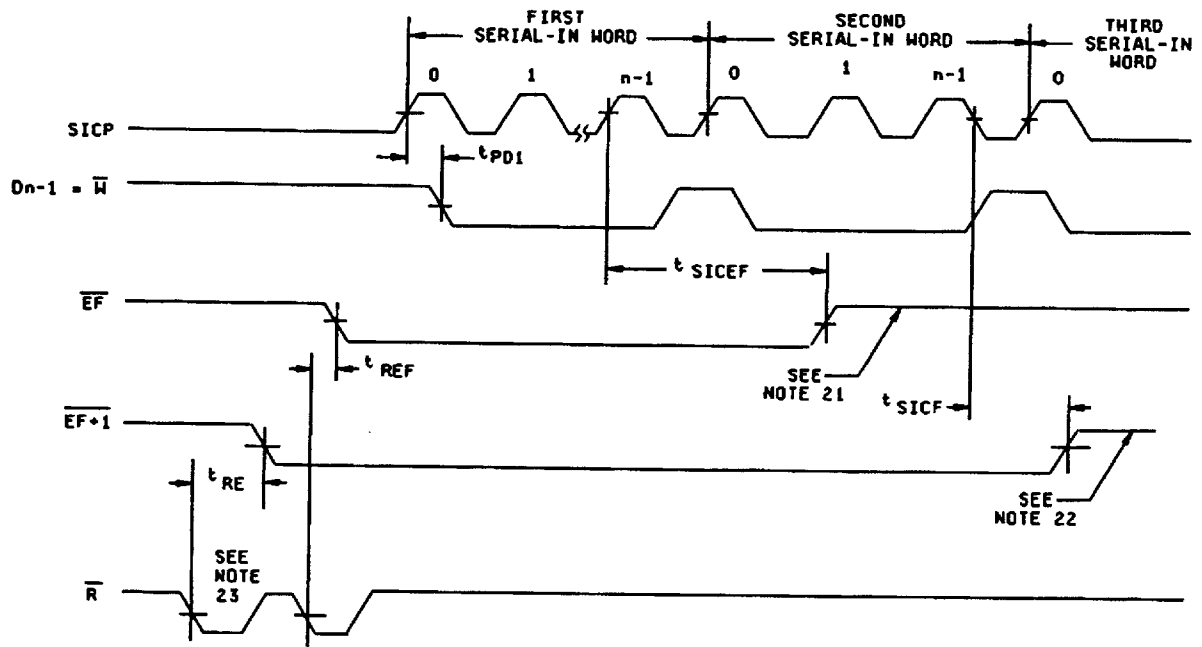


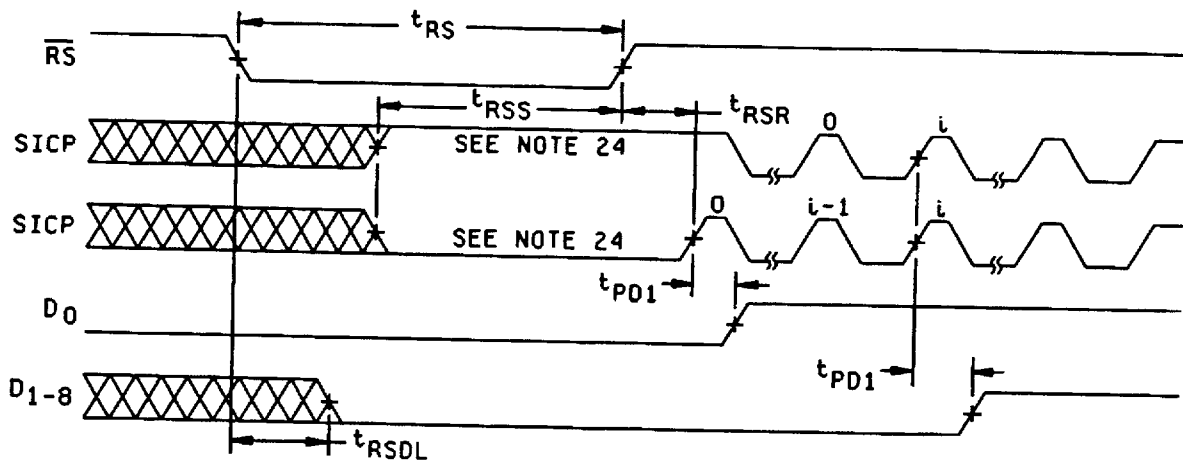
FIGURE 4. Timing waveforms - Continued.

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9004708 0002182 302

Reset timing for serial-in mode



Reset timing for serial-out mode

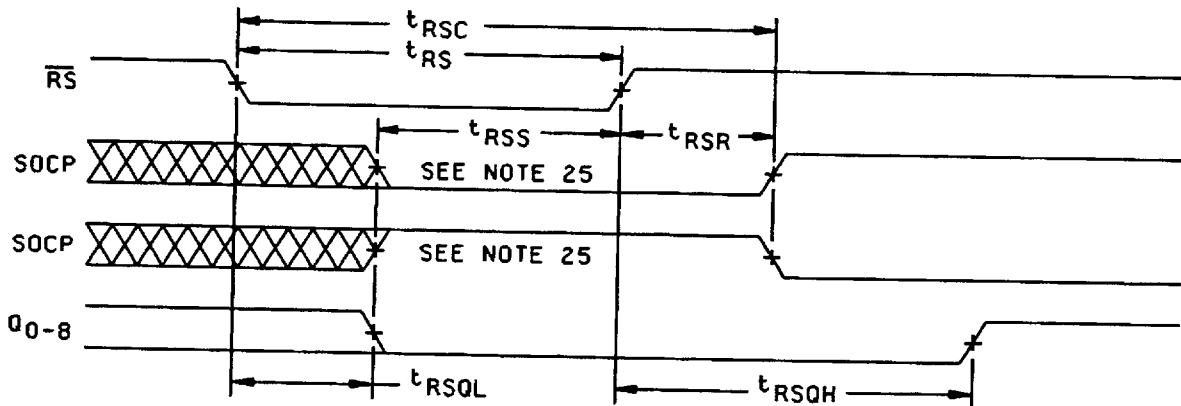


FIGURE 4. Timing waveforms - Continued.

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NOTES:

1. \overline{EF} , \overline{FF} and \overline{HF} may change status during reset, but flags will be valid at t_{RSC} .
2. \overline{EF} , \overline{FF} and \overline{HF} , \overline{AEF} , $\overline{FF-1}$, and $\overline{EF+1}$ may change status during retransmit, but flags will be valid at t_{RTC} .
3. Data is valid on this edge.
4. The empty flag is asserted by \overline{R} in the parallel-out mode and is specified by t_{REF} . The \overline{EF} flag is deasserted by the rising edge of \overline{W} .
5. First rising edge of write after \overline{EF} is set.
6. For the assertion time, t_{WFF} is used when data is written in the parallel mode. The \overline{FF} is deasserted by the rising edge of \overline{R} .
7. After $\overline{SO/PO}$ has been setup, it cannot be dynamically changed; it can only be changed after a reset operation.
8. For the stand alone mode, $n \geq 4$ and the input bits are numbered 0 to $n-1$.
9. After $\overline{SI/PI}$ has been setup, it cannot be dynamically changed; it can only be changed after a reset operation.
10. For the recommended interconnections, $\overline{D_1}$ is to be directly tied to \overline{W} and the t_{S4} and t_{H4} requirements will be satisfied. For users that modify \overline{W} externally, t_{S4} and t_{H4} have to be met.
11. The FIFO is full and a new read sequence is starting.
12. On the first rising edge of \overline{SOCP} , the \overline{FF} is deasserted. In the serial-in mode, a new write operation can begin after t_{RFFS1} after \overline{FF} goes HIGH. In the parallel-in mode, a new write operation can occur immediately after \overline{FF} flag goes HIGH.
13. The $\overline{FF-1}$ flag is deasserted after the first \overline{SOCP} of the second serial word.
14. \overline{SOCP} should not be clocked until \overline{EF} goes HIGH.
15. The empty flag is asserted in the serial-out mode by using the t_{SOCEF} parameter. This parameter is measured in the worst case from the rising edge of the \overline{SOCP} used to clock data bit 0. Whenever \overline{EF} goes LOW, there is only one word to be shifted out. In the parallel-in mode, the \overline{EF} flag is deasserted by the rising edge of \overline{W} . In the serial-in mode, the \overline{EF} flag is deasserted by the rising edge of \overline{W} .
16. Parallel write shown for reference only. Can also use serial input mode.
17. First write rising edge after \overline{EF} is set.
18. \overline{SICP} should not be clocked until \overline{FF} goes HIGH.
19. The full flag is asserted in the serial-in mode by using the t_{SICFF} parameter. This parameter is measured in the worst case from the rising edge of \overline{SICP} followed by a $(t_{PD1} + t_{WFF})$ delay from the first rising edge of \overline{SICP} of the last word.
20. First read rising edge after \overline{FF} is set.
21. The empty flag is deasserted when an entire word has been loaded into the internal RAM. It can occur after the first rising edge of \overline{SICP} of the second serial-in word. In the serial-out mode, a new read operation can begin after t_{REFSO} after \overline{EF} goes HIGH. In the parallel-out mode, a new read operation can occur immediately after \overline{FF} goes HIGH.
22. The $\overline{EF+1}$ flag is deasserted after the $n-1$ rising edge of \overline{SICP} of the third serial-in word.
23. Parallel read shown for reference only. Can also use serial output mode.
24. \overline{SICP} should be steady low or high during t_{RSS} . The first low to high or high to low transition can begin after t_{RSR} .
25. \overline{SOCP} should be steady low or high during t_{RSS} . The first low to high or high to low transition can begin after t_{RSR} .

FIGURE 4. Timing waveforms - Continued.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	---
Final electrical test parameters (method 5004)	1*,2,3,7*,8A, 8B,9,10,11
Group A test requirements (method 5005)	1,2,3,4**,7,8A, 8B,9,10,11
Groups C and D end-point electrical parameters (method 5005)	2,3,7,8A,8B

* PDA applies to subgroups 1 and 7.
** See 4.3.1c

3.8 Notification of change. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.9 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

(2) $T_A = +125^\circ\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.

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c. Subgroup 4 (C_{IN} and C_{OUT} measurement) shall be measured only for the initial test and after process or design changes which may affect input capacitance.

d. Subgroups 7 and 8 shall include verification of the truth table.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition C or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

(2) $T_A = +125^\circ\text{C}$, minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein).

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.

6.5 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

STANDARDIZED MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-89943
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